TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOSII)

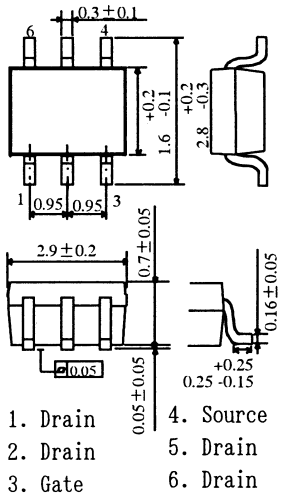
TPC6102

Notebook PC Applications

Portable Equipment Applications

- Low drain-source ON resistance: $R_{DS\ (ON)}$ = 48 mΩ (typ.)
- High forward transfer admittance: $|Y_{fs}|$ = 6 S (typ.)
- Low leakage current: I_{DSS} = −10 μA (max) (V_{DS} = −30 V)
- Enhancement mode: V_{th} = −0.8 to −2.0 V (V_{DS} = −10 V, I_D = −1 mA)

Unit: mm



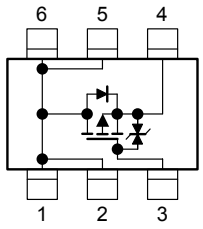
JEDEC	—
JEITA	—
TOSHIBA	2-3T1A

Weight: 0.011 g (typ.)

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	−30	V
Drain-gate voltage (R_{GS} = 20 kΩ)		V_{DGR}	−30	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC (Note 1)	I_D	−4.5	A
	Pulse (Note 1)	I_{DP}	−18	
Drain power dissipation (t = 5 s) (Note 2a)		P_D	2.2	W
Drain power dissipation (t = 5 s) (Note 2b)		P_D	0.7	W
Single pulse avalanche energy (Note 3)		E_{AS}	3.3	mJ
Avalanche current		I_{AR}	−2.25	A
Repetitive avalanche energy (Note 4)		E_{AR}	0.22	mJ
Channel temperature		T_{ch}	150	°C
Storage temperature range		T_{stg}	−55 to 150	°C

Circuit Configuration



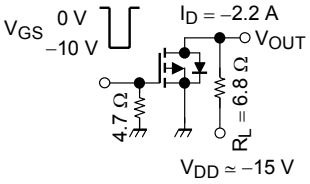
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	$R_{th\ (ch-a)}$	56.8	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	$R_{th\ (ch-a)}$	178.5	°C/W

Note 1, Note 2, Note 3, Note 4 and Note 5: See the next page.

This transistor is an electrostatic- ensitive device. Please handle with caution.

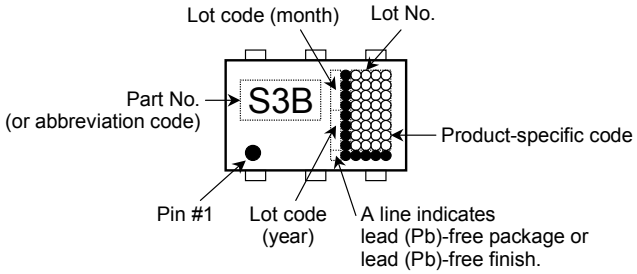
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	V_{GS} = ±16 V, V_{DS} = 0 V	—	—	±10	μA
Drain cut-OFF current		I_{DSS}	V_{DS} = −30 V, V_{GS} = 0 V	—	—	−10	μA
Drain-source breakdown voltage		$V_{(BR)\ DSS}$	I_D = −10 mA, V_{GS} = 0 V	−30	—	—	V
		$V_{(BR)\ DSX}$	I_D = −10 mA, V_{GS} = 20 V	−15	—	—	
Gate threshold voltage		V_{th}	V_{DS} = −10 V, I_D = −1 mA	−0.8	—	−2.0	V
Drain-source ON resistance		$R_{DS\ (ON)}$	V_{GS} = −4.5 V, I_D = −2.2 A	—	78	100	mΩ
		$R_{DS\ (ON)}$	V_{GS} = −10 V, I_D = −2.2 A	—	48	60	
Forward transfer admittance		$\|Y_{fs}\|$	V_{DS} = −10 V, I_D = −2.2 A	3.0	6.0	—	S
Input capacitance		C_{iss}	V_{DS} = −10 V, V_{GS} = 0 V, f = 1 MHz	—	500	—	pF
Reverse transfer capacitance		C_{rss}		—	110	—	
Output capacitance		C_{oss}		—	150	—	
Switching time	Rise time	t_r	 Duty ≦ 1%, t_w = 10 μs	—	3	—	ns
	Turn-ON time	t_{on}		—	7	—	
	Fall time	t_f		—	31	—	
	Turn-OFF time	t_{off}		—	79	—	
Total gate charge (gate-source plus gate-drain)		Q_g	V_{DD} ≃ −24 V, V_{GS} = −10 V, I_D = −4.5 A	—	11	—	nC
Gate-source charge		Q_{gs}		—	8.5	—	
Gate-drain (“miller”) charge		Q_{gd}		—	2.5	—	

Source-Drain Ratings and Characteristics (Ta = 25°C)

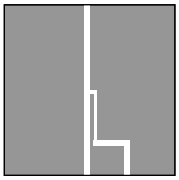
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Pulse drain reverse current	(Note 1)	I_{DRP}	—	—	—	−18	A
Forward voltage (diode)		V_{DSF}	I_{DR} = −4.5 A, V_{GS} = 0 V	—	—	1.2	V

Marking (Note 5)



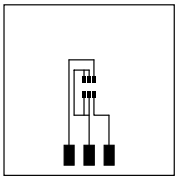
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)
(b) Device mounted on a glass-epoxy board (b) (t = 5 s)



FR-4
25.4 × 25.4 × 0.8
Unit: (mm)

(a)



FR-4
25.4 × 25.4 × 0.8
Unit: (mm)

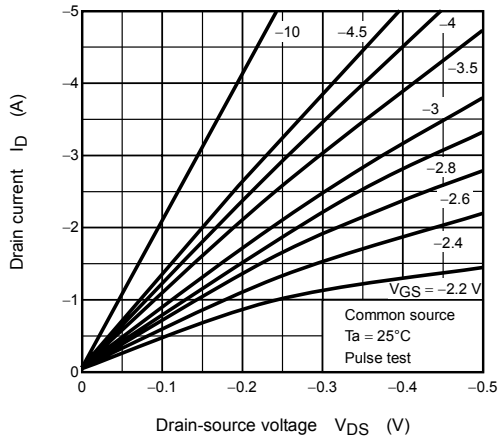
(b)

Note 3: V_{DD} = −24 V, T_{ch} = 25°C (initial), L = 0.5 mH, R_G = 25 Ω, I_{AR} = −2.25 A

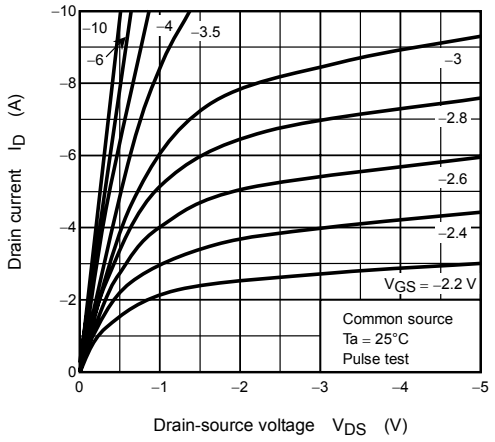
Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

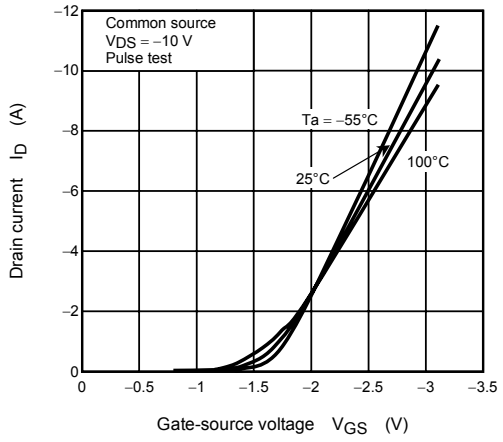
$I_D - V_{DS}$



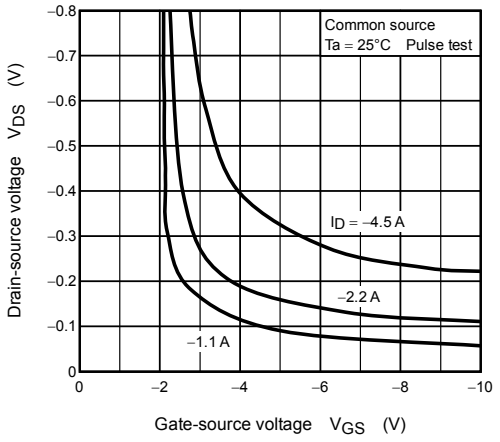
$I_D - V_{DS}$



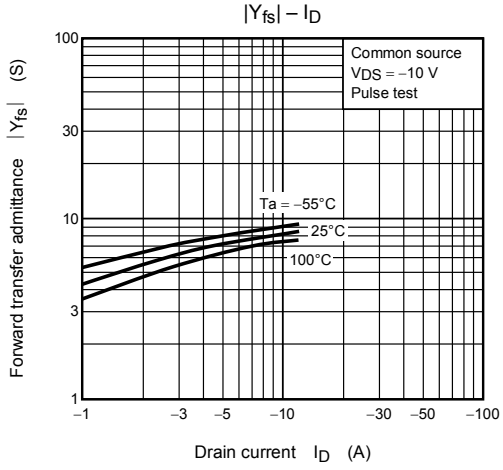
$I_D - V_{GS}$



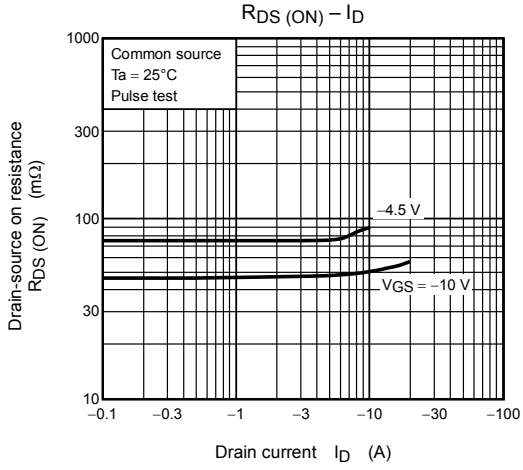
$V_{DS} - V_{GS}$



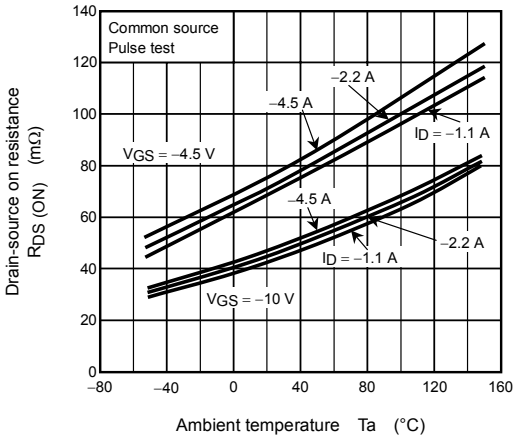
$|Y_{fs}| - I_D$



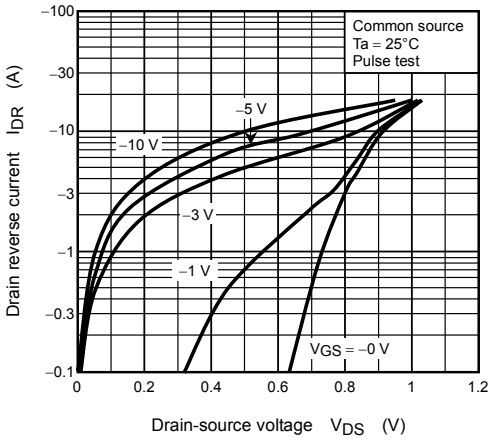
$R_{DS\ (ON)} - I_D$



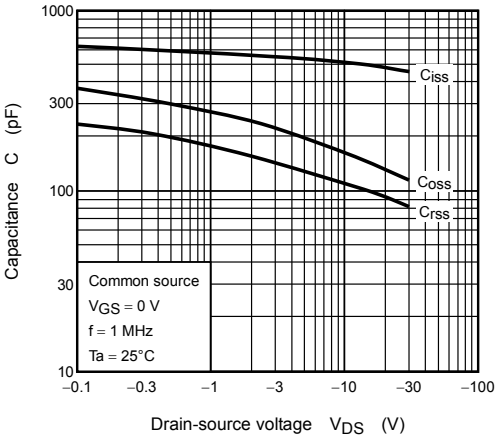
$R_{DS\ (ON)}$ – Ta



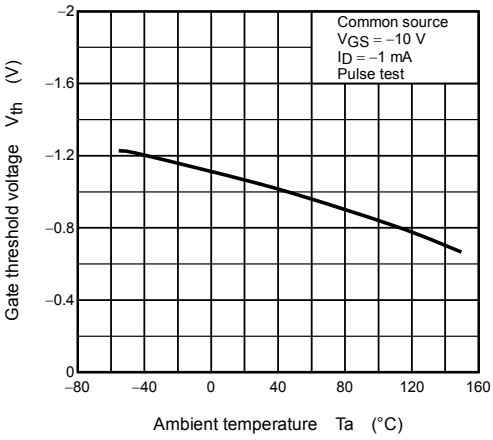
I_{DR} – V_{DS}



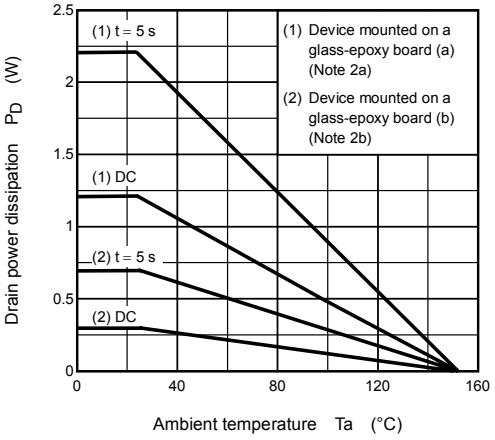
Capacitance – V_{DS}



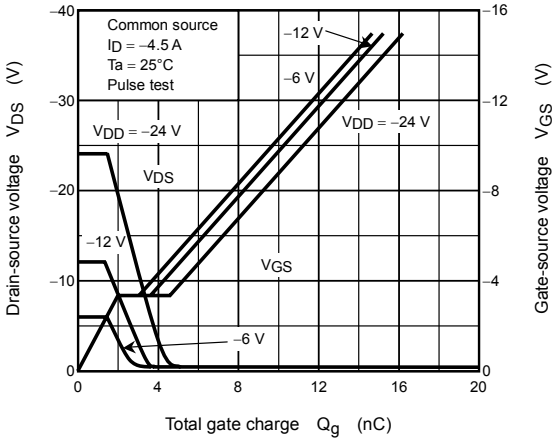
V_{th} – Ta



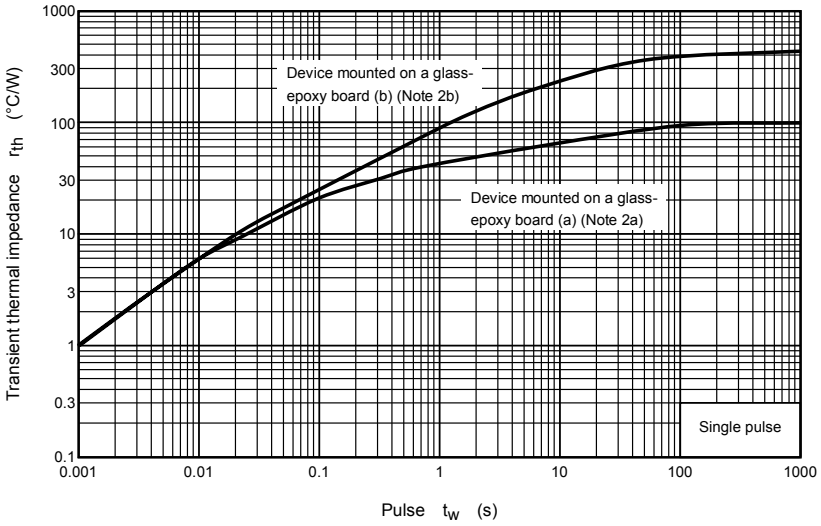
P_D – Ta



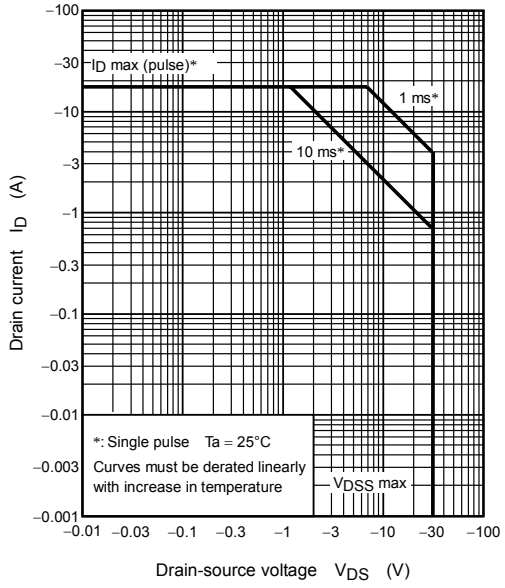
Dynamic input/output characteristics



$r_{th} - t_w$



Safe operating area



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